

REMARKS

Applicant thanks Examiner for the detailed remarks and analysis. Claims 1-3 and 11-14 remain in this application. Claims 4-10 and 15-19 have been cancelled. Claims 20-25 have been added, and claims 1 and 11 have been amended.

Claims 1-3 and 11-14 were rejected as being anticipated by Parkhill et al. (U.S. 2002/0034088), and alternatively as being anticipated by Schantz et al. (U.S. 5,517,063). Claims 1 and 11 now require a cold plate integrated into the module housing that includes a direct copper bonded substrate attached to a base plate by a solder layer. Parkhill et al. and Schantz et al. do not disclose or suggest these features. Accordingly, Applicant requests withdrawal of this rejection.

Applicant has added claims 20-25. Claims 20 and 23 require that the direct copper bonded substrate includes a first copper layer, a ceramic layer and a second copper layer fused together. Claims 21 and 24 require that the second copper layer is etched to form electrically isolated structures for selectively mounting circuit components. Claims 22 and 25 require that the base plate include a first side to which the solder layer is attached and a second side in thermal contact with a fluid channel for cooling circuit components mounted to the direct copper bonded substrate. These features are not disclosed or suggested by the cited prior art.

Accordingly, the claims are believed in condition for allowance. No additional fees are seen to be required. If any additional fees are due, however, the Commissioner is authorized to charge Deposit Account No. 50-1482, in the name of Carlson, Gaskey & Olds, P.C., for any additional fees or credit the account for any overpayment. Therefore, favorable reconsideration and allowance of this application is respectfully requested.

Respectfully Submitted,

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